

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	57	hartig-klaus.in.	US-PGPUB; USPAT	OR	ON	2005/12/08 20:34
L3	22	hartig-klaus.in.	EPO; JPO; DERWENT	OR	ON	2005/12/08 20:34
S7	315	over\$1spray with (gun ion laser beam)	US-PGPUB; USPAT	OR	ON	2005/12/06 14:59
S8	17	over\$1spray with (gun ion laser beam) with (remov\$3 etch\$3)	US-PGPUB; USPAT	OR	ON	2005/12/06 14:56
S9	118	S7 and ("118"/\$.ccls. 204/298.\$.ccls.)	US-PGPUB; USPAT	OR	ON	2005/12/06 15:00
S10	315	over\$1spray with (gun ion laser beam)	US-PGPUB; USPAT	OR	ON	2005/12/06 18:04
S11	8	S10 and ("118"/715-733.ccls. 204/298.\$.ccls.)	US-PGPUB; USPAT	OR	ON	2005/12/06 18:04
S12	0	("2004/0175511").URPN.	USPAT	OR	ON	2005/12/06 18:12
S13	35	(118/718.ccls. 118/719.ccls. 204/298.23-298.26.ccls. 156/345.31.ccls. 156/345.32.ccls.) and (ion with (remov\$3 etch\$3) with (under below underside bottom))	USPAT	OR	ON	2005/12/06 18:44
S14	43	(118/718.ccls. 118/719.ccls. 204/298.23-298.26.ccls. 156/345.31.ccls. 156/345.32.ccls.) and (ion with (remov\$3 etch\$3) with (under below underside bottom))	US-PGPUB; USPAT	OR	ON	2005/12/06 18:15
S15	48	(118/718.ccls. 118/719.ccls. 204/298.23-298.26.ccls. 156/345.31.ccls. 156/345.32.ccls.) and ((laser beam ion) with (remov\$3 etch\$3) with (under below underside bottom))	US-PGPUB; USPAT	OR	ON	2005/12/06 18:38
S16	251	(ion with (beam gun) with (remov\$3 etch\$3) with (under below underside bottom) with (substrate sheet plate semiconductor wafer workpiece))	US-PGPUB; USPAT	OR	ON	2005/12/06 18:39
S17	198	(ion with (beam gun) with (remov\$3 etch\$3) with (under below underside bottom) with (substrate sheet plate semiconductor wafer workpiece)) same (coat\$3 deposit\$3 film\$3 form\$3)	US-PGPUB; USPAT	OR	ON	2005/12/06 18:40
S18	17	(ion with (beam gun) with (remov\$3 etch\$3) with (under below underside bottom) with (substrate sheet plate semiconductor wafer workpiece)) same ((coat\$3 deposit\$3 film\$3 form\$3) same (transfer\$4 travel\$4 translat\$4 mov\$3 convey\$4))	US-PGPUB; USPAT	OR	ON	2005/12/06 18:41
S19	281	(118/718.ccls. 118/719.ccls. 204/298.23-298.26.ccls. 156/345.31.ccls. 156/345.32.ccls.) and ((remov\$3 etch\$3 clean\$3) with (under below underside bottom) with (substrate wafer plate semiconductor workpiece sheet))	USPAT	OR	ON	2005/12/06 18:45
S20	355	(118/718.ccls. 118/719.ccls. 204/298.23-298.26.ccls. 156/345.31.ccls. 156/345.32.ccls. 216/37.ccls. 427/255.5.ccls.) and ((remov\$3 etch\$3 clean\$3) with (under below underside bottom) with (substrate wafer plate semiconductor workpiece sheet))	USPAT	OR	ON	2005/12/06 18:46
S21	94	(118/718.ccls. 118/719.ccls. 204/298.23-298.26.ccls. 156/345.31.ccls. 156/345.32.ccls. 216/37.ccls. 427/255.5.ccls.) and ((remov\$3 etch\$3 clean\$3) with (under below underside bottom) with (substrate wafer plate semiconductor workpiece sheet) with (transfer\$4 travel\$4 translat\$4 mov\$3 convey\$4))	USPAT	OR	ON	2005/12/06 18:59
S22	29	("20020102352" "20040020761" "3904506" "3925182" "3968018" "4214972" "4604181" "5054421" "5273634" "5424130" "5616532" "5853866" "5874701" "5879519" "5939194" "5961843" "5969470" "5982101" "6013372" "6090489" "6139803" "6150755" "6165256" "6171659" "6191062" "6210779" "6224718" "6225747" "6368664" "6652974" "6660365").PN.	USPAT	OR	ON	2005/12/06 19:54
S23	2	("4188199" "5520740").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 19:51

S24	27	("3968018").URPN.	USPAT	OR	ON	2005/12/06 20:08
S25	0	10/429,967	USPAT	OR	ON	2005/12/06 20:18
S26	0	216/37.ccls. and (ion with beam with mill)	USPAT	OR	ON	2005/12/06 20:19
S27	6	216/37.ccls. and (ion with beam with mill\$3)	USPAT	OR	ON	2005/12/06 20:19
S28	32	216/37.ccls. and (ion with beam)	USPAT	OR	ON	2005/12/06 20:19
S29	40	216/37.ccls. and (ion with beam)	US-PGPUB; USPAT	OR	ON	2005/12/06 20:33
S30	4	216/37.ccls. and ((ion with beam) with (opposite bottom under under\$1side lower beneath))	US-PGPUB; USPAT	OR	ON	2005/12/06 20:20
S31	282	"216"/\$.ccls. and ((ion with beam) with (perimeter edge bevel under\$1side beneath lower bottom under))	US-PGPUB; USPAT	OR	ON	2005/12/06 20:34
S32	185	"216"/\$.ccls. and ((ion with beam) with (perimeter edge bevel under\$1side beneath lower bottom under) with (remov\$3 clean\$3 etch\$3 mill\$3))	US-PGPUB; USPAT	OR	ON	2005/12/06 20:35
S33	185	"216"/\$.ccls. and ((ion with beam) with (perimeter edge bevel under\$1side beneath lower bottom under margin\$3) with (remov\$3 clean\$3 etch\$3 mill\$3))	US-PGPUB; USPAT	OR	ON	2005/12/06 20:35
S34	112	"216"/\$.ccls. and ((ion with beam) with (perimeter edge bevel under\$1side beneath lower bottom under margin\$3) with (remov\$3 clean\$3 etch\$3 mill\$3) with (coat\$3 film deposit\$3 layer))	US-PGPUB; USPAT	OR	ON	2005/12/06 20:48
S35	5	("4666554").URPN.	USPAT	OR	ON	2005/12/06 20:39
S36	81	((ion with beam) with (perimeter edge bevel under\$1side beneath lower bottom under margin\$3) with surface with (remov\$3 clean\$3 etch\$3 mill\$3) with (coat\$3 film deposit\$3 layer))	EPO; JPO; DERWENT	OR	ON	2005/12/06 20:48
S37	2	((ion with beam) with (perimeter edge bevel under\$1side beneath lower bottom under margin\$3) with surface with (remov\$3 clean\$3 etch\$3 mill\$3) with (coat\$3 film deposit\$3 layer)) same (transfer\$4 translat\$4 convey\$4 mov\$4 travel\$4)	EPO; JPO; DERWENT	OR	ON	2005/12/06 20:49
S38	20	((ion with beam) with (perimeter edge bevel under\$1side beneath lower bottom under margin\$3) with surface with (remov\$3 clean\$3 etch\$3 mill\$3) with (coat\$3 film deposit\$3 layer)) same (transfer\$4 translat\$4 convey\$4 mov\$4 travel\$4)	US-PGPUB; USPAT	OR	ON	2005/12/06 20:54
S39	56	427/255.5.ccls. and (ion with beam)	US-PGPUB; USPAT	OR	ON	2005/12/06 20:55
S40	11	427/255.5.ccls. and (ion with beam with (remov\$3 clean\$3 etch\$3))	US-PGPUB; USPAT	OR	ON	2005/12/06 20:59
S41	25	(ion with beam with (remov\$3 clean\$3 etch\$3) with bottom with surface with (substrate semiconductor wafer workpiece sheet))	US-PGPUB; USPAT	OR	ON	2005/12/06 21:07
S42	0	("2004/0020761").URPN.	USPAT	OR	ON	2005/12/06 21:02
S43	11	(ion with beam with (remov\$3 clean\$3 etch\$3) with bottom with surface with (substrate semiconductor wafer workpiece sheet))	EPO; JPO; DERWENT	OR	ON	2005/12/06 21:07
S44	1	(ion with beam with (remov\$3 clean\$3 etch\$3) with bevel)	EPO; JPO; DERWENT	OR	ON	2005/12/06 21:07
S45	1369	(118/718.ccls. 118/719.ccls.) and (ion with beam with (remov\$3 clean\$3 etch\$3) surface with (substrate semiconductor wafer workpiece sheet))	US-PGPUB; USPAT	OR	ON	2005/12/06 21:08
S46	9	(118/718.ccls. 118/719.ccls.) and (ion with beam with (remov\$3 clean\$3 etch\$3) with surface with (substrate semiconductor wafer workpiece sheet))	US-PGPUB; USPAT	OR	ON	2005/12/06 21:09
S47	4	ion with beam with (remov\$3 clean\$3 etch\$3) with bottom with surface with (substrate semiconductor wafer workpiece sheet) with (after subsequent post) with (coat\$3 deposit\$3 film form\$3)	US-PGPUB; USPAT	OR	ON	2005/12/06 21:38

S48	0	ion with beam with (remov\$3 clean\$3 etch\$3) with bottom with surface with (substrate semiconductor wafer workpiece sheet) with (after subsequent post) with (coat\$3 deposit\$3 film form\$3)	EPO; JPO; DERWENT	OR	ON	2005/12/06 21:10
S49	88	204/298.26.cds. and (ion with beam)	US-PGPUB; USPAT	OR	ON	2005/12/06 21:23
S50	1	"4851095".pn.	US-PGPUB; USPAT	OR	ON	2005/12/06 21:23
S51	94	ion with beam with (post) with (treat\$4 process\$4)	US-PGPUB; USPAT	OR	ON	2005/12/06 21:38
S52	25	ion with beam with (post) with (treat\$4 process\$4) with (remov\$3 clean\$3 etch\$3)	US-PGPUB; USPAT	OR	ON	2005/12/06 21:43
S53	101	204/298.35.cds. and 204/298.23-298.26.cds.	US-PGPUB; USPAT	OR	ON	2005/12/06 21:44
S54	44	118/718.cds. and (ion with beam)	US-PGPUB; USPAT	OR	ON	2005/12/06 21:44
S55	3	118/718.cds. and (ion with beam) with (below under)	US-PGPUB; USPAT	OR	ON	2005/12/06 21:45
S56	38	(118/718.cds. 118/719.cds.) and (ion with beam) with (remov\$3 etch\$3 clean\$3)	US-PGPUB; USPAT	OR	ON	2005/12/06 21:45
S57	5	("5958134").URPN.	USPAT	OR	ON	2005/12/06 21:49
S58	18	("3562140" "3968018" "4626336" "4663009" "4722298" "4749465" "4882028" "5032243" "5048191" "5056227" "5088202" "5110249" "5121660" "5129289" "5142785" "5232568" "5377816").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/06 21:50
S59	62	156/345.39	US-PGPUB; USPAT	OR	ON	2005/12/07 11:22
S60	26	(back\$1side with etch\$3 with ion with (gun beam))	US-PGPUB; USPAT	OR	ON	2005/12/07 11:28
S61	31	(back\$1side with etch\$3 with ion with (gun beam mill\$3))	US-PGPUB; USPAT	OR	ON	2005/12/07 11:25
S62	5	S61 not S60	US-PGPUB; USPAT	OR	ON	2005/12/07 11:28
S63	3	(remov\$3 with (extra inadvertent\$4 mistak\$4) with etch\$3 with ion with (gun beam))	US-PGPUB; USPAT	OR	ON	2005/12/07 11:54
S64	22	(remov\$3 with (extra inadvertent\$4 mistak\$4) with ion with (mill\$3 gun beam))	US-PGPUB; USPAT	OR	ON	2005/12/07 12:32
S65	36	156/345\$.cds. and ((back\$1side) with (etch\$3 mill ion beam gun) with remov\$4)	US-PGPUB; USPAT	OR	ON	2005/12/07 12:08
S66	36	156/345\$.cds. and ((back\$1side) with (etch\$3 mill\$3 ion beam gun) with remov\$4)	US-PGPUB; USPAT	OR	ON	2005/12/07 12:09
S67	2	156/345\$.cds. and ((back\$1side) with (mill\$3 ion beam gun) with remov\$4)	US-PGPUB; USPAT	OR	ON	2005/12/07 12:09
S68	20	("5707485").URPN.	USPAT	OR	ON	2005/12/07 12:10
S69	3	("4624728" "4908095" "5075256").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 12:11
S70	17	("5075256").URPN.	USPAT	OR	ON	2005/12/07 12:12
S71	4	(remov\$3 with (extra inadvertent\$4 mistak\$4) with ion with (mill\$3 gun beam))	EPO; JPO; DERWENT	OR	ON	2005/12/07 12:34
S72	376	216/66.cds. and (ion with (mill\$3 gun beam))	US-PGPUB; USPAT	OR	ON	2005/12/07 12:35
S73	147	216/66.cds. and (ion with (mill\$3 gun beam) with (back\$1side back under beneath underneath below lower under\$1side bottom))	US-PGPUB; USPAT	OR	ON	2005/12/07 12:37
S74	6	("4825808" "5062021" "5322595" "5520981" "5586040" "5599590").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 13:36

S75	3	("5910235").URPN.	USPAT	OR	ON	2005/12/07 12:49
S76	10	("6210981").URPN.	USPAT	OR	ON	2005/12/07 13:28
S77	1028	guardian.as.	USPAT	OR	ON	2005/12/07 13:28
S78	72	guardian.as. and (ion adj beam)	USPAT	OR	ON	2005/12/07 13:28
S79	37	guardian.as. and (ion adj beam) with (bottom under under\$1side below beneath under\$1neath reverse back back\$1side)	USPAT	OR	ON	2005/12/07 13:30
S80	37	guardian.as. and ((ion adj beam) with (bottom under under\$1side below beneath under\$1neath reverse back back\$1side))	USPAT	OR	ON	2005/12/07 13:30
S81	151	(118/719.ccls. 118/718.ccls.) and (ion with (beam mill gun))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 15:31
S82	18	(118/719.ccls. 118/718.ccls.) and (ion with (beam mill gun) with remov\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 13:40
S83	4	(156/345.32.ccls. 156/345.31.ccls.) and (ion with (beam mill gun) with remov\$4)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 13:40
S84	12	((118/718.ccls. 118/719.ccls.) and (156/345.32.ccls. 156/345.31.ccls.)) and (ion with (beam mill gun))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 13:42
S85	233	((118/718.ccls. 118/719.ccls.) and (156/345.32.ccls. 156/345.31.ccls.))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 13:43
S86	11	((118/718.ccls. 118/719.ccls.) and (156/345.32.ccls. 156/345.31.ccls.)) and (remov\$4 with (excess\$4 over\$1spray extra inadvertent\$4 mistake\$4))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 13:44
S87	11	((118/718.ccls. 118/719.ccls.) and (156/345.32.ccls. 156/345.31.ccls.)) and ((remov\$4 etch\$3) with (excess\$4 over\$1spray extra inadvertent\$4 mistake\$4))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 13:47
S88	87	((118/718.ccls. 118/719.ccls.) and (156/345.32.ccls. 156/345.31.ccls.)) and ((remov\$4 etch\$3) with (bottom under under\$1side below beneath under\$1neath reverse back back\$1side))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 13:47
S89	499	(427/255.5).CCLS.	US-PGPUB; USPAT	OR	OFF	2005/12/07 13:52
S90	70	427/255.5.ccls. and (ion with (beam etch\$3 mill\$3 gun))	US-PGPUB; USPAT	OR	ON	2005/12/07 14:24
S91	56	427/532.ccls. and (ion with (beam etch\$3 mill\$3 gun))	US-PGPUB; USPAT	OR	ON	2005/12/07 14:25
S92	9	427/532.ccls. and (ion with (beam etch\$3 mill\$3 gun) with remov\$4)	US-PGPUB; USPAT	OR	ON	2005/12/07 14:34
S93	32	427/533.ccls. and (ion with (beam etch\$3 mill\$3 gun) with remov\$4)	US-PGPUB; USPAT	OR	ON	2005/12/07 14:28
S94	32	S93 not33	US-PGPUB; USPAT	OR	ON	2005/12/07 14:34
S95	31	S93 not S91	US-PGPUB; USPAT	OR	ON	2005/12/07 14:34
S96	1	427/209-210.ccls. and (ion with (beam etch\$3 mill\$3 gun) with remov\$4)	US-PGPUB; USPAT	OR	ON	2005/12/07 14:35
S97	10	427/209-210.ccls. and (ion with (beam etch\$3 mill\$3 gun))	US-PGPUB; USPAT	OR	ON	2005/12/07 14:37
S98	865	427/209-210.ccls.	US-PGPUB; USPAT	OR	ON	2005/12/07 14:35
S99	9	427/209.ccls. and (ion with (beam etch\$3 mill\$3 gun))	US-PGPUB; USPAT	OR	ON	2005/12/07 14:37

S10 0	675	427/209.cds.	US-PGPUB; USPAT	OR	ON	2005/12/07 14:37
S10 1	0	427/209.cds. and ((remov\$3 etch\$3 mill\$3) with (excess\$4extra inadvertent\$4 mistak\$4))	US-PGPUB; USPAT	OR	ON	2005/12/07 14:38
S10 2	70	427/209.cds. and ((remov\$3 etch\$3 mill\$3) with (excess\$4extra inadvertent\$4 mistak\$4))	US-PGPUB; USPAT	OR	ON	2005/12/07 15:15
S10 3	196	(118/719.cds. 118/718.cds.) and in\$1line	US-PGPUB; USPAT	OR	ON	2005/12/07 15:30
S10 4	2121	(118/719.cds. 118/718.cds.)	US-PGPUB; USPAT	OR	ON	2005/12/07 15:31
S10 5	155	(118/719.cds. 118/718.cds.) and (ion with (beam mill\$3 gun))	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 15:31
S10 6	3	("5439524" "5505779" "5863338").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 15:39
S10 7	3	("5439524" "5505779" "5863338").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 15:39
S10 8	0	("6231673").URPN.	USPAT	OR	ON	2005/12/07 15:39
S10 9	9	("3594238" "4478703" "4629631" "4683149" "4708037" "4740385" "5241152" "5346600").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 15:42
S11 0	0	("2003/0150382").URPN.	USPAT	OR	ON	2005/12/07 15:48
S11 1	0	204/298.56.cds. and (ion with (beam mill\$3 gun))	USPAT	OR	ON	2005/12/07 15:48
S11 2	77	204/298.26.cds. and (ion with (beam mill\$3 gun))	USPAT	OR	ON	2005/12/07 15:49
S11 3	128	204/298.36.cds.	USPAT	OR	ON	2005/12/07 15:49
S11 4	143	204/298.36.cds.	US-PGPUB; USPAT	OR	ON	2005/12/07 15:49
S11 5	4	204/298.36.cds. and 204/298.23-298.26.cds.	US-PGPUB; USPAT	OR	ON	2005/12/07 16:29
S11 6	15	204/298.36.cds. and (204/298.23-298.26.cds. 204/298.35.cds.)	US-PGPUB; USPAT	OR	ON	2005/12/07 16:25
S11 7	16	("4278493").URPN.	USPAT	OR	ON	2005/12/07 15:52
S11 8	12	("3528387" "3548189" "3769109" "3868271" "4016062" "4098917" "4126530" "4135998" "4147573" "4148705").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/07 16:03
S11 9	143	204/298.36.cds.	US-PGPUB; USPAT	OR	ON	2005/12/07 16:35
S12 0	11	204/298.36.cds. and 204/298.35.cds.	US-PGPUB; USPAT	OR	ON	2005/12/07 16:29
S12 1	4	204/298.36.cds. and back\$1side	US-PGPUB; USPAT	OR	ON	2005/12/07 16:36
S12 2	1	glass and (ion with (beam gun etch\$3 mill\$3)) with back\$1side	EPO; JPO; DERWENT	OR	ON	2005/12/07 16:37
S12 3	33	(ion with (beam gun etch\$3 mill\$3)) with back\$1side	EPO; JPO; DERWENT	OR	ON	2005/12/07 16:40
S12 4	1	(ion with (beam gun etch\$3 mill\$3)) and back\$1side and in\$1line	EPO; JPO; DERWENT	OR	ON	2005/12/07 16:40
S12 5	2	(ion with (beam gun etch\$3 mill\$3)) and back\$1side and ((transfer\$4 translat\$4 convey\$4 mov\$4 travel\$4) with (substrate wafer sheet plate semiconductor glass))	EPO; JPO; DERWENT	OR	ON	2005/12/07 16:42

S12 6	112	((ion with (beam gun etch\$3 mill\$3)) with (back\$1side beneath under under\$1neath bottom lower)) and ((transfer\$4 translat\$4 convey\$4 mov\$4 travel\$4) with (substrate wafer sheet plate semiconductor glass))	EPO; JPO; DERWENT	OR	ON	2005/12/07 16:43
S12 7	70	((ion with (beam gun etch\$3 mill\$3)) with (back\$1side bottom lower)) and ((transfer\$4 translat\$4 convey\$4 mov\$4 travel\$4) with (substrate wafer sheet plate semiconductor glass))	EPO; JPO; DERWENT	OR	ON	2005/12/07 19:28
S12 8	1	("3925182").PN.	US-PGPUB; USPAT	OR	OFF	2005/12/07 19:30
S12 9	1	("5879519").PN.	US-PGPUB; USPAT	OR	OFF	2005/12/07 19:30
S13 0	26	"0200564"	EPO; JPO; DERWENT	OR	ON	2005/12/07 19:34
S13 1	7	"200200564"	EPO; JPO; DERWENT	OR	ON	2005/12/07 19:49
S13 2	1	("6660635").PN.	US-PGPUB; USPAT	OR	OFF	2005/12/07 19:50
S13 3	1	("6660365").PN.	US-PGPUB; USPAT	OR	OFF	2005/12/07 19:50
S13 4	42	(bevel chamfer) with (ion with (gun beam etch\$3 mill\$3))	US-PGPUB; USPAT	OR	ON	2005/12/07 20:06
S13 5	69	(bevel chamfer\$3) with (ion with (gun beam etch\$3 mill\$3))	US-PGPUB; USPAT	OR	ON	2005/12/07 20:06
S13 6	37	(bevel chamfer\$3) with (ion with (gun beam mill\$3))	US-PGPUB; USPAT	OR	ON	2005/12/07 20:10
S13 7	108	(remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (bevel chamfer\$3)	US-PGPUB; USPAT	OR	ON	2005/12/07 20:17
S13 8	28	(remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (bevel chamfer\$3)	EPO; JPO; DERWENT	OR	ON	2005/12/07 20:12
S13 9	0	(remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (bevel chamfer\$3) with beam	US-PGPUB; USPAT	OR	ON	2005/12/07 20:12
S14 0	0	(remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (bevel chamfer\$3) with ion	US-PGPUB; USPAT	OR	ON	2005/12/07 20:12
S14 1	596	(remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (bevel chamfer\$3 edge) with (back back\$1side under under\$1neath bottom lower)	US-PGPUB; USPAT	OR	ON	2005/12/07 20:20
S14 2	3820	(remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (bevel chamfer\$3 edge)	US-PGPUB; USPAT	OR	ON	2005/12/07 20:17
S14 3	13	(remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (bevel chamfer\$3 edge) with (back back\$1side under under\$1neath bottom lower) with (ion beam mill\$3 gun)	US-PGPUB; USPAT	OR	ON	2005/12/07 20:18
S14 4	157	((remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (bevel chamfer\$3 edge) with (back back\$1side under under\$1neath bottom lower)) and glass	US-PGPUB; USPAT	OR	ON	2005/12/07 20:20
S14 5	23	((remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (bevel chamfer\$3 edge) with (back back\$1side under under\$1neath bottom lower)) and (glass with sheet)	US-PGPUB; USPAT	OR	ON	2005/12/07 20:24
S14 6	588	((remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (back back\$1side under under\$1neath bottom lower)) and (glass with sheet)	US-PGPUB; USPAT	OR	ON	2005/12/07 20:28
S14 7	4	((remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (back back\$1side under under\$1neath bottom lower) with (ion gun beam)) and (glass with sheet)	US-PGPUB; USPAT	OR	ON	2005/12/07 20:25
S14 8	290	((remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (back back\$1side under under\$1neath bottom lower) with (ion gun beam))	US-PGPUB; USPAT	OR	ON	2005/12/07 20:25

S149	13	((remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (back back\$1side under under\$1neath bottom lower) with (ion with (gun beam)))	US-PGPUB; USPAT	OR	ON	2005/12/07 20:26
S150	13	((remov\$3 etch\$3) with (extra excess\$3 mistak\$4 inadvertent\$4) with (back back\$1side under under\$1neath bottom lower)) and (glass with sheet)	EPO; JPO; DERWENT	OR	ON	2005/12/07 20:30
S151	1	("3551128").PN.	US-PGPUB; USPAT	OR	OFF	2005/12/07 20:31
S152	2	((("0035512") or ("0000028"))).PN.	US-PGPUB; USPAT	OR	OFF	2005/12/07 20:31
S153	1	("3551228").PN.	US-PGPUB; USPAT	OR	OFF	2005/12/07 20:36
S154	0	65/67.cds. and (ion with (beam gun mill\$3))	US-PGPUB; USPAT	OR	ON	2005/12/07 20:36
S155	238	"65"/\$.cds. and (ion with (beam gun mill\$3))	US-PGPUB; USPAT	OR	ON	2005/12/07 20:36
S156	30	"65"/\$.cds. and (ion with (beam gun mill\$3) with remov\$3)	US-PGPUB; USPAT	OR	ON	2005/12/08 11:20
S157	269	etch\$3 with marginal	US-PGPUB; USPAT	OR	ON	2005/12/08 11:20
S158	12	etch\$3 with marginal with ion	US-PGPUB; USPAT	OR	ON	2005/12/08 11:21
S159	182	etch\$3 with edge with (excess\$3 extra inadvertent mistak\$3)	US-PGPUB; USPAT	OR	ON	2005/12/08 11:22
S160	34	etch\$3 with edge with (excess\$3 extra inadvertent mistak\$3)	EPO; JPO; DERWENT	OR	ON	2005/12/08 11:32
S161	3	ion with (gun beam) with edge with (excess\$3 extra inadvertent mistak\$3)	EPO; JPO; DERWENT	OR	ON	2005/12/08 11:33
S162	6	ion with (gun beam) with edge with (excess\$3 extra inadvertent mistak\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 11:35
S163	8	ion with (gun beam) with bottom with surface with (excess\$3 extra inadvertent mistak\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 11:36
S164	1	etch\$3 with (gun beam) with bottom with surface with (excess\$3 extra inadvertent mistak\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 11:37
S165	85	etch\$3 with bottom with surface with (excess\$3 extra inadvertent mistak\$3)	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 11:39
S166	13	etch\$3 with bottom with surface with (excess\$3 extra inadvertent mistak\$3)	EPO; JPO; DERWENT	OR	ON	2005/12/08 12:17
S167	81	204/192.34.cds.	EPO; JPO; DERWENT	OR	ON	2005/12/08 12:17
S168	417	204/192.34.cds.	US-PGPUB; USPAT	OR	ON	2005/12/08 12:17
S169	122	204/192.34.cds. and glass	US-PGPUB; USPAT	OR	ON	2005/12/08 12:18
S170	0	204/192.34.cds. and (glass same (bottom edge lower back back\$1side) with remov\$3)	US-PGPUB; USPAT	OR	ON	2005/12/08 12:18
S171	0	204/192.34.cds. and (glass same (bottom edge lower back back\$1side circumference perimeter bevel chamfer) with remov\$3)	US-PGPUB; USPAT	OR	ON	2005/12/08 12:19
S172	98	204/192.34.cds. and ((bottom edge lower back back\$1side circumference perimeter bevel chamfer) with remov\$3)	US-PGPUB; USPAT	OR	ON	2005/12/08 12:19
S173	38	204/192.34.cds. and ((bottom edge lower back back\$1side circumference perimeter bevel chamfer) with remov\$3 with surface)	US-PGPUB; USPAT	OR	ON	2005/12/08 12:25

S17 4	111	204/192.34.cds. and ((beam gun) with (below under underneath))	US-PGPUB; USPAT	OR	ON	2005/12/08 12:25
S17 5	63	204/192.34.cds. and ((beam gun) near4 (below under underneath))	US-PGPUB; USPAT	OR	ON	2005/12/08 12:26
S17 6	43	204/192.34.cds. and (204/192.11)	US-PGPUB; USPAT	OR	ON	2005/12/08 12:26
S17 7	44	204/192.34.cds. and 204/192.11.cds.	US-PGPUB; USPAT	OR	ON	2005/12/08 12:50
S17 8	10	("5472566").URPN.	USPAT	OR	ON	2005/12/08 12:31
S17 9	4	("4128765" "4411733" "5009743" "5223109").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 12:33
S18 0	249	(204/192.34.cds. 204/192.11.cds.) and (both with (side surface))	US-PGPUB; USPAT	OR	ON	2005/12/08 12:52
S18 1	60	(204/192.34.cds. 204/192.11.cds.) and (both with (side surface) with (process\$3 treat\$3))	US-PGPUB; USPAT	OR	ON	2005/12/08 12:52
S18 2	102	(204/192.34.cds. 204/192.11.cds.) and (both adj (side surface))	US-PGPUB; USPAT	OR	ON	2005/12/08 12:52
S18 3	47	(204/192.34.cds. 204/192.11.cds.) and ((both adj (side surface)) with (process\$3 treat\$3 ion))	US-PGPUB; USPAT	OR	ON	2005/12/08 12:53
S18 4	11	("4747922").URPN.	USPAT	OR	ON	2005/12/08 12:56
S18 5	20	("3391071" "3409529" "3472751" "3487000" "3492215" "3528387" "4142958" "4250009" "4278493" "4361472" "4381453" "4424103" "4450031" "4492620").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 12:57
S18 6	8	("4717622" "4840844" "4861662" "4880687" "4889767" "5118577" "5227211" "5275850").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/12/08 13:00
S18 7	10	("5500296").URPN.	USPAT	OR	ON	2005/12/08 13:58
S18 8	2	maloney.in. and bevel	USPAT	OR	ON	2005/12/08 13:59
S18 9	1	maloney.in. and (transfer\$4 with wet)	USPAT	OR	ON	2005/12/08 13:59
S19 0	0	maloney.in. and (transfer\$4 with robot)	USPAT	OR	ON	2005/12/08 13:59
S19 1	2	maloney.in. and (transfer\$4 with hand)	USPAT	OR	ON	2005/12/08 14:00
S19 2	42	maloney.in. and (blade)	USPAT	OR	ON	2005/12/08 14:01
S19 3	1	"6231428".pn.	USPAT	OR	ON	2005/12/08 14:33
S19 4	2	trojan.in. and scrub	USPAT	OR	ON	2005/12/08 15:29
S19 5	1	("6267853").PN.	US-PGPUB; USPAT	OR	OFF	2005/12/08 15:30
S19 6	1	("6161054").PN.	US-PGPUB; USPAT	OR	OFF	2005/12/08 15:30